micron Educator Hub

Intro to Fabrication Quiz

Reviewed 2025



© 2020-2025 Micron Technology, Inc. All rights reserved. Information, products, and/or specifications are subject to change without notice. All information is provided on an "AS IS" basis without warranties of any kind. Statements regarding products, including statements regarding product features, availability, functionality, or compatibility, are provided for informational purposes only and do not modify the warranty, if any, applicable to any product. Drawings may not be to scale. Micron, the Micron logo, and other Micron trademarks are the property of Micron Technology, Inc. All other trademarks are the property of their respective owners.

Copyright guidelines

By using any content provided by the Micron Educator Hub, you acknowledge that Micron Technology, Inc. ("Micron") is the sole owner of the content and agree that any use of the content provided by the Micron Educator Hub must comply with applicable laws and require strict compliance with these Guidelines:

- 1. Credit shall be expressly stated by you to Micron for use of the content, including any portion thereof, as follows:
 - a. "© 2020-2025 Micron Technology, Inc. All Rights Reserved. Used with permission."
- 2. You may not use the content in any way or manner other than for educational purposes.
- 3. You may not modify the content without approval by Micron.
- 4. You may not use the content in a manner which disparages or is critical of Micron, its employees, or Micron's products/services.
- 5. Permission to use the content may be canceled/terminated by Micron at any time upon written notice from Micron to You if You fail to comply with the terms herein.
- 6. You acknowledge and agree that the content is provided by Micron to You on an "as is" basis without any representations or warranties whatsoever, and that Micron shall have no liability whatsoever arising from Your use of the content. Micron shall ensure that the content does not violate any statutory provisions and that no rights of third parties are infringed by the content or its publication. Otherwise, liability of the parties shall be limited to intent and gross negligence.
- 7. You acknowledge and agree that the content is the copyrighted material of Micron and that the granting of permission by Micron to You as provided for herein constitutes the granting by Micron to You of a non-exclusive license to use the content strictly as provided for herein and shall in no way restrict or affect Micron's rights in and/or to the content, including without limitation any publication or use of the content by Micron or others authorized by Micron.
- 8. Except for the above permission, Micron reserves all rights not expressly granted, including without limitation any and all patent and trade secret rights. Except as expressly provided herein, nothing herein will be deemed to grant, by implication, estoppel, or otherwise, a license under any of Micron's other existing or future intellectual property rights.

How to cite sources from the Micron Educator Hub

- Micron is committed to collaborate with Educators to make semiconductor memory education resources available through the Micron Educator Hub.
- The content in the Micron Educator Hub has been identified by Micron as current and relevant to our company.
- Please refer to the table on the right for proper citation.

Use case	How to cite sources
a) Whole slide deck or whole document	No additional citation required.
Description: User uses the whole slide deck or whole document AS IS, without any modification	
b) Full slide or full page	"© 2020-2025 Micron Technology, Inc. All Rights Reserved. Used with permission."
Description: User incorporates a full slide or a full page into their own slide deck or document.	
c) Portion of a slide or portion of a page	This is not allowed.
Description: User copies a portion of a slide or a portion of a page into a new slide or page	

Intro to Fabrication – Quiz Ideas

- 1) What is the purpose of the CMP (Chemical Mechanical Planarization) area?
- A. Deposit a planar film on the wafer
- B. Remove films or topography
- C. Oxidize the wafer
- D. Add impurities to the silicon lattice
- 2) What Fab Area sees the wafer the most in a typical Traveler?
 - A. Photolithography
 - B. Implant
 - C. PVD (Physical Vapor Deposition)
 - D. Wet Process

- 3) Which of these Fab Areas is most likely to process a wafer after a Photo pattern has been printed on photoresist?
 - A. CMP (Chemical Mechanical Planarization)
 - B. PVD (Physical Vapor Deposition)
 - C. Dry Etch
 - D. Diffusion
- 4) Which of the Fab Areas listed here deposits temporarily a film on the wafer?
 - A. CMP (Chemical Mechanical Planarization)
 - B. Metrology
 - C. RDA (Real-time Defect Analysis)
 - D. Photolithography

Intro to Fabrication – Quiz Ideas

- 5) Which of these groups of Fab Areas is typically used to deposit films on wafer? Select the best answer.
 - A. CVD, PVD, and Diffusion
 - B. Implant, Photolithography, and CMP
 - C. Diffusion, Dry Etch, and Wet Process
 - D. CVD, Photolithography and RDA
- 6) Critical Dimensions, Film Thickness, Film composition and Stress are examples of processes performed by what Fab Area?
 - A. Probe Testing
 - B. Parametric Testing
 - C. Metrology
 - D. RDA (Real-time Defect Analysis)

- 7) Which of these is NOT true?
 - A. Dry Etch can perform anisotropic etches
 - B. Wet Process can perform anisotropic etches
 - C. Dry etch can pattern features smaller than what Photo can pattern
 - D. Wet Process is used to remove unwanted films and impurities
- 8) Phosphorous and Arsenic are examples of:
 - A. Dopants added to the wafer in the Implant Area
 - Films deposited in the CVD (Chemical Vapor Deposition) Area
 - C. Elements with 4 valence electrons (electrons in the outer shell)
 - D. Elements present in the photoresist

Intro to Fabrication – Quiz Ideas

- 9) Which of these statements is TRUE about a reticle?
 - A. A reticle has the pattern we want to print on the photoresist
 - B. The reticle is the lens system in the Photolithography equipment tool
 - C. Reticle is synonymous with Photoresist
 - D. The reticle is used as a hard mask for Dry Etch
- 10) If you have a deep trench with a high aspect ratio and you need to <u>conformally</u> deposit a thin film in the trench, which of these Fab Areas may NOT be the best choice for this process?
 - A. CVD (Chemical Vapor Deposition)
 - B. Diffusion
 - C. PVD (Physical Vapor Deposition)

Educator Hub

micron

© 2020-2025 Micron Technology, Inc. All rights reserved. Information, products, and/or specifications are subject to change without notice. All information is provided on an "AS IS" basis without warranties of any kind. Statements regarding products, including statements regarding product features, availability, functionality, or compatibility, are provided for informational purposes only and do not modify the warranty, if any, applicable to any product. Drawings may not be to scale. Micron, the Micron logo, and other Micron trademarks are the property of Micron Technology, Inc. All other trademarks are the property of their respective owners.